



SAW Wafer Specification

<i>CUSTOMER:</i>		Travel Code	Product'n Code
<i>PO Number:</i>			
<i>SPECIFICATION:</i>			
<i>DIAMETER:</i>	100 mm	+/- 0.5	
<i>THICKNESS:</i>	0.500 mm	+/- 0.025	
<i>THETA:</i>	X cut	+/- 18 arcmin	
<i>PHI:</i>	X cut	+/- 18 arcmin	
<i>REF FLAT:</i>	112.2° from Z axis	+/- 18 arcmin	Std Orientation
<i>FLAT WIDTH:</i>	32.5 mm	+/- 1.0	
<i>AUX FLAT:</i>	12 mm 90 deg CW	+/- 1.0 mm +/- 30 min	9:00 o'clock
<i>LASER SCRIBE:</i>	none		
<i>TTV:</i>	12 microns	Max	5 point
<i>BOW:</i>	+/- 50 microns	Max	Exc 3mm
<i>FRONT SIDE:</i>	SAW Grade Mirror Polish		
<i>BACK SIDE:</i>	Ra 1.5 μ	nominal	Sandblast
<i>BEVEL:</i>	SEMI std include flat		
<i>CHIPS:</i>	0.25 mm	Max	
<i>MATERIAL:</i>	Lithium Tantalate		
<i>CURRIE TEMP:</i>	605.0° C	+/- 2.0 °	
<i>SHIP DATA:</i>	Cert. of C. /Cert of Origin Data sheet Curie temp Dimensions Orientation Bow, TTV, Surface roughness		
<i>LABEL:</i>			